

RS Pro 1805314

2-Part Dispensable Thermal Gap Filler, 2.0W/mK



Physical Properties	Value
Colour	Part A - yellow, part B - white
Thermal conductivity W/m.K (ASTM D5470)	1.8
Volume resistivity Ohm-m	10 ¹²
Specific gravity g/cm ³	2.7
Dielectric breakdown kV/mm	>10
Dielectric constant	7
Heat capacity J/mK	1
Flammability	V-0
Application temperature °C	-60 to +200
Hardness	40
Tensile strength MPa	0.2
Elongation %	100

Surface cure thermal interface paste specially designed to resist pumping out from the bond line. It can be applied using industrial dispensing equipment or via screen/stencil printing techniques.

Features

- Long term thermal stability,
- recommended for applications with rapid temperature cycling,
- easily dispensable,
- fast curing time (when heated).

Curing Data	Value
Curing Schedule 1	24hr @25degC
Curing Schedule 2	100min @80degC
Curing Schedule 3	10min @100degC
Working Time	30min @25degC

Part Number	Size
1805314	200+200ml syringe

Applications

Automotive ECU (electronic control units), power supplies, microprocessors, displays and consumer electronics

